

Appl. No. 10/749,028  
Arndt dated August 10, 2005  
Reply to Office Action of May 10, 2005

**Amendments to the Specification:**

**Please replace the paragraph on page 27, lines 28-32 with the following amended paragraph:**

Figure 9 illustrates a probe card assembly 900 which includes as its major functional components a probe card 902, an interposer 904, and an interconnection substrate 906 which may be a spacc transformer, which is suitable in use for making reversible interconnections to elongate interconnection elements 926 extending from semiconductor devices resident on a semiconductor wafer 908, which may be (but is not required to be) an unsingulated wafer.